

IN THE CLAIMS:

Please cancel claims 3 and 13 without prejudice. Please amend claims 1, 2, 4 through 7, 11, 12, and 14 as follows:

b1 1. (Amended) A three-layered, laminated circuit structure, comprising:

a first substrate having conductive via through holes disposed therein;

a second substrate laminated to said first substrate and having conductive, adhesive-filled via through holes that align with, and make electrical contact with, the conductive via through holes of said first substrate; and

a third substrate laminated to said second substrate having via through holes that align with, and make electrical contact with, the adhesive filled via through holes of said second substrate, thus forming said three-layered, laminated circuit structure.

m2 2. (Twice Amended) The three-layered circuit structure in accordance with claim 1, wherein said first and third

substrates each comprise a signal core layer, and said second substrate comprises a power core layer.

b3 4. (Twice Amended) The three-layered circuit structure in accordance with claim 2, wherein said via through holes of said power core layer comprises undercut contact surfaces, and said via through holes of each of said signal core layers have metallic pads that make electrical contact with said undercut contact surfaces of said via through holes of said power core layer.

b4 5. (Amended) A multi-layered circuit structure, comprising:

a first substrate having conductive via through holes disposed therein; and

a second substrate laminated to said first substrate, and having via through holes comprising conductive adhesive coated pads that align with, and make electrical contact with, the conductive via through holes of said first substrate.

b5 6. (Twice Amended) The multi-layered circuit structure in accordance with claim 5, wherein said first substrate

comprises a signal core layer, and said second substrate comprises a power core layer.

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7. (Twice Amended) The multi-layered circuit structure in accordance with claim 5, further comprising a third substrate having similar structure to that of said first substrate, said first and third substrates each being laminated to said second substrate, and wherein said first and third substrates each define a signal core layer, said second substrate further defining an inner power core layer sandwiched between each of said signal core layers.

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11. (Amended) A multi-layered circuit structure, comprising:

first and second substrates, each having conductive via through holes disposed therein; and

a third substrate laminated between said first and second substrates and having conductive, adhesive-filled via through holes that align with, and make electrical contact with, the conductive via through holes of said first and second substrates.

12. (Amended) The multi-layered circuit structure in accordance with claim 11, wherein said first and second